CLAIMS

What is claimed is:

- 1 1. A method of creating a conductive path between two or 2 more conductive layers, wherein the conductive layers 3 are separated by one or more dielectric layers, the method comprising: 5 exposing portions of at least two conductive layers; 6 applying a conductive material to the exposed portions 7 of the conductive layers, the conductive material 8 creating an electrical coupling between the 9 conductive layers; and 10 grounding at least one of the conductive layers to a 11 controlled ground potential.
- 1 2. A method as recited in claim 1, wherein the portions
 2 of the conductive layers are exposed by recessing at
 3 least one of the conductive layers and any dielectric
 4 layers positioned between the conductive layers, the
 5 conductive material overhanging an uppermost of the
 6 conductive layers.

- 1 3. A method as recited in claim 2, wherein a material of
- one or more of the conductive layers is copper and a
- 3 material of one or more of the conductive layers is
- 4 stainless steel.
- 1 4. A method as recited in claim 2, wherein the conductive
- 2 material is selected from a group consisting of solder
- 3 and a conductive adhesive.
- 1 5. A method as recited in claim 2, wherein one or more of
- 2 the conductive layers is grounded to a controlled
- 3 ground potential using one or more dedicated ground
- 4 paths etched from one or more of the conductive
- 5 layers.
- 1 6. A method as recited in claim 1, wherein the exposed
- 2 portion of at least one of the conductive layers
- includes a through-hole, where the conductive material
- 4 is a rivet extending through the through hole.
- 1 7. A method as recited in claim 6, wherein the rivet
- 2 creates a grounding path between a top grounded layer
- 3 and one or more of the underlying conductive layers.

- 1 8. A method as recited in claim 6, wherein a material of
- one or more of the conductive layers is copper and a
- 3 material of one or more of the conductive layers is
- 4 stainless steel.
- 1 9. A method as recited in claim 6, wherein one or more of
- 2 the conductive layers is grounded to a controlled
- ground potential using one or more dedicated ground
- 4 paths etched from one or more of the conductive
- 5 layers.
- 1 10. A method as recited in claim 1, wherein the conductive
- 2 material is a finger formed by etching, the finger
- 3 extending from an uppermost of the conductive layers
- 4 and pressed onto the exposed portion of an underlying
- 5 conductive layer.
- 1 11. A method as recited in claim 10, wherein a material of
- one or more of the conductive layers is copper and a
- 3 material of one or more of the conductive layers is
- 4 stainless steel.

- 1 12. A method as recited in claim 10, wherein one or more
- of the conductive layers is grounded to a controlled
- 3 ground potential using one or more dedicated ground
- 4 paths etched from one or more of the conductive
- 5 layers.
- 1 13. A method as recited in claim 10, wherein the finger is
- 2 welded and place.
- 1 14. A method as recited in claim 1, wherein the conductive
- 2 material is a finger formed by etching, the finger
- 3 being sandwiched between a mount plate and an arm.
- 1 15. A method as recited in claim 14, wherein a material of
- one or more of the conductive layers is copper and a
- 3 material of one or more of the conductive layers is
- 4 stainless steel.
- 1 16. A method as recited in claim 14, wherein one or more
- of the conductive layers is grounded to a controlled
- 3 ground potential using one or more dedicated ground
- 4 paths etched from one or more of the conductive
- 5 layers.

- 1 17. A method as recited in claim 14, wherein the finger is
- welded in place.
- 1 18. A method as recited in claim 1, wherein the conductive
- 2 material is a finger formed by etching, the finger
- 3 being sandwiched between a mount plate and a load
- 4 beam.
- 1 19. A method as recited in claim 18, wherein a material of
- one or more of the conductive layers is copper and a
- 3 material of one or more of the conductive layers is
- 4 stainless steel.
- 1 20. A method as recited in claim 18, wherein one or more
- of the conductive layers is grounded to a controlled
- ground potential using one or more dedicated ground
- 4 paths etched from one or more of the conductive
- 5 layers.
- 1 21. A method as recited in claim 18, wherein the finger is
- welded in place.

- 1 22. A method as recited in claim 1, further comprising an
- 2 extraneous conductive layer, the conductive material
- 3 being a dimple extending from the extraneous
- 4 conductive layer and contacting the exposed portions
- of the conductive layers.
- 1 23. A method as recited in claim 22, wherein the dimple
- 2 extends through a via in at least one of the
- 3 conductive layers.
- 1 24. A method as recited in claim 22, wherein a material of
- one or more of the conductive layers is copper and a
- 3 material of one or more of the conductive layers is
- 4 stainless steel.
- 1 25. A method as recited in claim 22, wherein one or more
- of the conductive layers is grounded to a controlled
- ground potential using one or more dedicated ground
- 4 paths etched from one or more of the conductive
- 5 layers.
- 1 26. A method as recited in claim 1, wherein the portions
- of the conductive layers are exposed by punching a

- 3 hole through the conductive layers, the conductive
- 4 material extending through the hole.
- 1 27. A method as recited in claim 26, wherein a material of
- one or more of the conductive layers is copper and a
- 3 material of one or more of the conductive layers is
- 4 stainless steel.
- 1 28. A method as recited in claim 26, wherein one or more
- of the conductive layers is grounded to a controlled
- ground potential using one or more dedicated ground
- 4 paths etched from one or more of the conductive
- 5 layers.